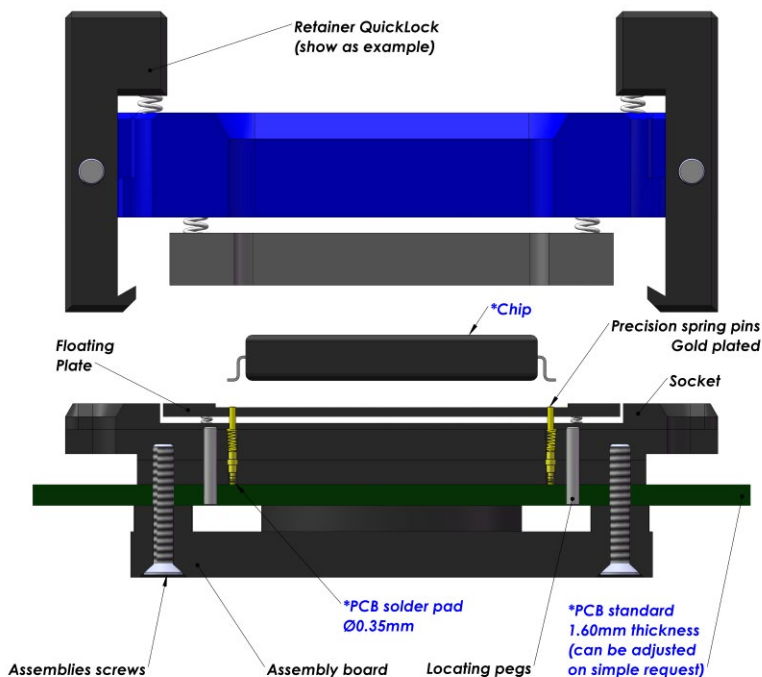
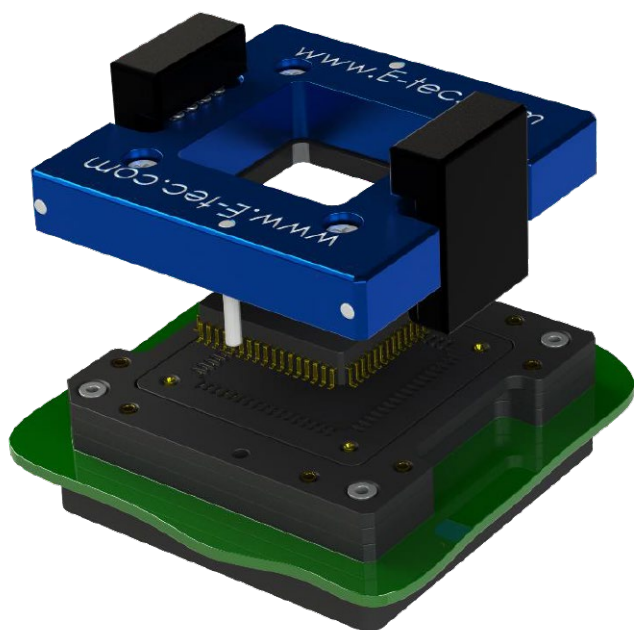
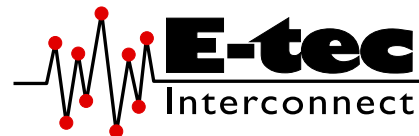


Probe Pin Solderless Compression Test Socket

For SOP / DSO / SOIC / QFP / xQFP Package

0.50 mm pitch (from 0.50 mm to 0.79 mm)



E-tec Interconnect AG is the world leading Test socket manufacturer

Probe Pin (Pogo) Solderless compression Test Sockets type are available for any chip size and pitch and are attached with 2, 4 or 8 screws to the PCB. The assembly board ensures perfect coplanarity of the socket. Contact reliability is guaranteed with spring loaded gold plated contacts, which are pressed onto gold plated PCB pads. Probe Pin (Pogo) Solderless compression type sockets are available with all retention systems. We aim to solve your requirements. Please note, we will always request the chip data to ensure we offer a compatible socket.

Contacts Specifications						
Contact type code	0590	0591	0592	0593	0594	0598
Application	Standard	Long live	High Frequency	High Temp & Long live	High Power	SuperHigh Frequency
Mounting	Solderless	Solderless	Solderless	Solderless	Solderless	Solderless
Bandwidth (GHz@-1dB)	3 GHz	7 GHz	29 GHz	8.9 GHz	9 GHz	40 GHz
Contact resistance	<100 mOhm	40 mOhm	100 mOhm	80 mOhm	80 mOhm	100 mOhm
Chip contact tip shape	Single Point tip Concave tip	Crown tip	Single Point tip	Crown tip	Crown tip	Single Point tip
PCB tip shape	Single Point tip	Single Point tip	Single Point tip	Single Point tip	Single Point tip	Spring
Force	30 gr	23 gr	20 gr	23 gr	30 gr	20 gr
Current rating	1.5 A	1 A	1.5 A	2 A	2 A	0.5 A
Capacitance pF	<1 pF	0.45 pF	0.48 pF	0.71 pF	na	0.36 pF
Inductance nH	<2 nH	1.08 nH	0.89 nH	0.67 nH	na	1.19 nH
Impedance Ohms	38 Ω	39 Ω	38 Ω	55 Ω	60 Ω	62 Ω
Temperature range	-55°C to +150°C	-50°C to +150°C	-40°C to +120°C	-50°C to +220°C	-50°C to +220°C	-55°C to +150°C
Mating cycles	100 K	300 K	100 K	500 K	500 K	100 K

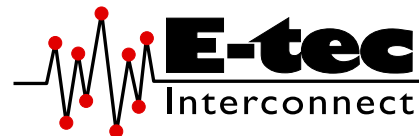
More on the next page



Probe Pin Solderless Compression Test Socket

For SOP / DSO / SOIC / QFP / xQFP Package

0.50 mm pitch (from 0.50 mm to 0.79 mm)

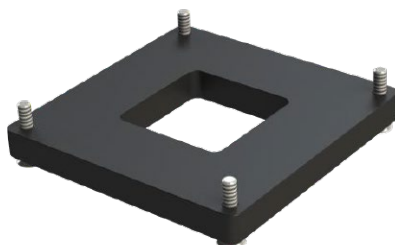


Standard assembly boards

Small Chip size



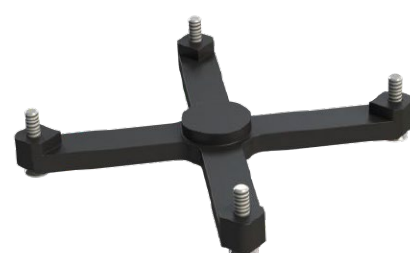
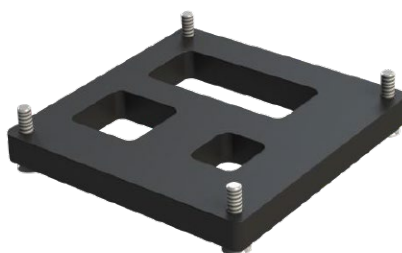
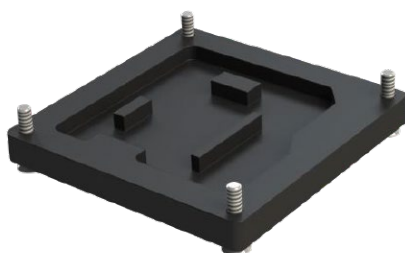
Medium Chip size



Large Chip size



Custom assembly boards



How to order

QU # # # # -059# - # # # # # 55L #

Shape of tip
U : Concave
Options:
P : Pointed

Nbr of contacts
 Depends on ballcount of chip

Contact type
91 to 98 : See "Contacts specification" chart
90 : Standard solderless compression style
9M : Special mixed contact style

Plating
55L: Gold + Locating pegs
 Other on request

Option code (see page 16-19)
D : Dead bug
M : Multi frames
U : Multi packages
S : Custom opening slot
H : Heatsink
F : Fan + Heatsink
P : Thermal drain pad
W : Transparent lid
I : Steel retention lid
B : Aluminium retention lid
T : Torque tool fixture
G : Handling button

Retention frame type (Lid) (see page 12-15)
S : ScrewLock
F : FastLock
B : SpringLock
H : Open Clamshell Alu (<200 contacts)
J : Clamshell Alu (>200 contacts)
L : Open Lever Clamshell Alu (>200 contacts)
Q : Open QuickLock (<200 contacts)
D : QuickLock (>200 contacts)
M : Injection Molded ClamShell

Grid code / Config. code
 Will be given by the factory after receipt of the chip datasheet

